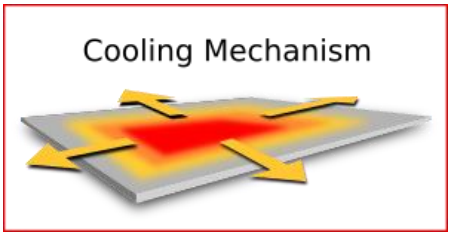
Technical Data - HB160TC

Product description

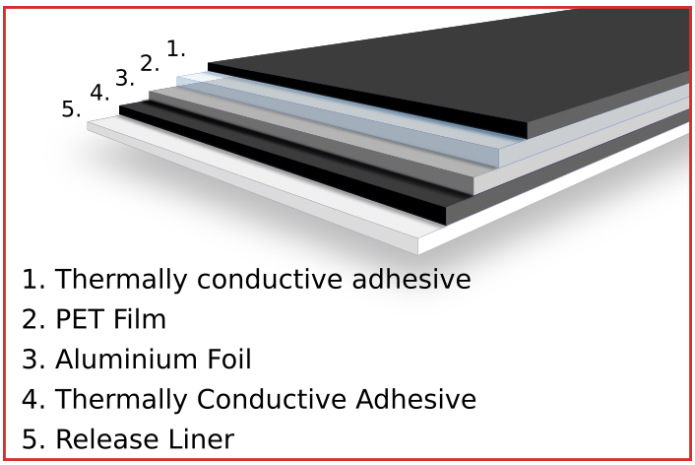
Thermal spread & interface double sided tape, a newly developed material with excellent heat spread / diffusion properties and very good dielectric and absorption characteristics. The tape stabilizes the function of the device it is applied to, reducing malfunction through high temperatures emmited from specific components.



- Superior thermal conductivity in the plane
- Quick heat spread with graphite adhesive
- Excellent adhesion and stability
- Excellent electrical conductivity

Construction

Property	Value
Backing Type	Heat Radiation coating + Aluminium Foil
Adhesive	Thermally Conductive adhesive (Graphite filler)
Release liner	Paper liner



Technical data

Item	Unit	Spec.	Test Method
Total thickness	mm	0.160 ± 10%	Thickness Gauge
Adhesive strength	Gram / mm	> 700	KS T1028(SUS304)
Top-Bottom Resistance (Z axis)	Ω	Non-Conductive	MIL-DTL-83528C
Surface Resistance, Adhesive (XY axis)	Ω	Non-Conductive	MIL-DTL-83528C
Thermal conductivity (Vertical)	W/m-K	4	ASTM D 5470
Thermal conductivity (In-Plane)	W/m-K	180	ASTM D 5470
Operating Temperature	°C	-10~90	-

Application: Dual CPU Core, Battery (Cover), Shield Can, LCD & Camera module for Mobilephone, LED Lighting, LED TV, Tablet PC & etc. And can be used for various thin heat spreader.

Unless stated otherwise all values given are average. All of the tapes in our range should be thoroughly tested on the substrates in the particular application they are intended for. Hi-Bond Tapes Ltd. will not be responsible for product failure unless full testing has been completed. The customer has to decide on the tapes suitability for the intended application.

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